



# REPETITIVE AVALANCHE AND dv/dt RATED HEXFET®TRANSISTORS THRU-HOLE (TO-204AA)

**500V, N-CHANNEL** 

**Product Summary** 

Part Number	BV <sub>DSS</sub>	RDS(on)	I <sub>D</sub>
IRF440	500V	$0.85\Omega$	8.0A



## Description

HEXFET® MOSFET technology is the key to IR Hirel advanced line of power MOSFET transistors. The efficient geometry and unique processing of this latest "State of the Art" design achieves: very low on-state resistance combined with high trans conductance; superior reverse energy and diode recovery dv/dt capability.

The HEXFET transistors also feature all of the well established advantages of MOSFETs such as voltage control, very fast switching and temperature stability of the electrical parameters. They are well suited for applications such as switching power supplies, motor controls, inverters, choppers, audio amplifiers and high energy pulse circuits.

#### **Features**

- Repetitive Avalanche Ratings
- Dynamic dv/dt Rating
- · Hermetically Sealed
- Simple Drive Requirements
- ESD Rating: Class 2 per MIL-STD-750, Method 1020

## **Absolute Maximum Ratings**

Symbol	Parameter	Value	Units	
I <sub>D1</sub> @ V <sub>GS</sub> = 10V, T <sub>C</sub> = 25°C	Continuous Drain Current	8.0		
I <sub>D2</sub> @ V <sub>GS</sub> = 10V, T <sub>C</sub> = 100°C	Continuous Drain Current	5.0	Α	
I <sub>DM</sub> @T <sub>C</sub> = 25°C	Pulsed Drain Current ①	32		
P <sub>D</sub> @T <sub>C</sub> = 25°C	Maximum Power Dissipation	125	W	
	Linear Derating Factor	1.0	W/°C	
V <sub>GS</sub>	Gate-to-Source Voltage	± 20	V	
E <sub>AS</sub>	Single Pulse Avalanche Energy ②	700	mJ	
I <sub>AR</sub>	Avalanche Current ①	8.0	Α	
E <sub>AR</sub>	Repetitive Avalanche Energy ①	12.5	mJ	
dv/dt	Peak Diode Recovery ③	3.5	V/ns	
T <sub>J</sub>	Operating Junction and	-55 to + 150		
T <sub>STG</sub>	Storage Temperature Range	-55 to + 150	°C	
	Lead Temperature	300 (0.063 in. (1.6mm) from case for 10s)		
	Weight	11.5 (Typical)	g	

For footnotes refer to the page 2.



## Electrical Characteristics @ Tj = 25°C (Unless Otherwise Specified)

Symbol	Parameter	Min.	Тур.	Max.	Units	Test Conditions
BV <sub>DSS</sub>	Drain-to-Source Breakdown Voltage	500			V	$V_{GS} = 0V, I_D = 1.0mA$
$\Delta BV_{DSS}/\Delta T_{J}$	Breakdown Voltage Temp. Coefficient		0.78		V/°C	Reference to 25°C, I <sub>D</sub> = 1.0mA
R <sub>DS(on)</sub>	Static Drain-to-Source On-Resistance			0.85	Ω	V <sub>GS</sub> = 10V, I <sub>D2</sub> = 5.0A ④
				0.98		$V_{GS} = 10V, I_{D1} = 8.0A$ ④
$V_{GS(th)}$	Gate Threshold Voltage	2.0		4.0	V	$V_{DS} = V_{GS}$ , $I_D = 250\mu A$
Gfs	Forward Transconductance	4.7			S	V <sub>DS</sub> = 15V, I <sub>D2</sub> = 5.0A ④
I <sub>DSS</sub>	Zero Gate Voltage Drain Current			25	μA	$V_{DS} = 400V, V_{GS} = 0V$
	Zelo Gate Voltage Diaili Guilent			250	μΛ	$V_{DS} = 400V, V_{GS} = 0V, T_{J} = 125^{\circ}C$
$I_{GSS}$	Gate-to-Source Leakage Forward			100	nA	V <sub>GS</sub> = 20V
	Gate-to-Source Leakage Reverse			-100	117 (	V <sub>GS</sub> = -20V
$Q_G$	Total Gate Charge	27.3		68.5		$I_{D1} = 8.0A$
$Q_{GS}$	Gate-to-Source Charge	2.0		12.5	nC	V <sub>DS</sub> = 250V
$Q_{GD}$	Gate-to-Drain ('Miller') Charge	11		42		V <sub>GS</sub> = 10V
$t_{d(on)}$	Turn-On Delay Time			21		V <sub>DD</sub> = 250V
tr	Rise Time			73	20	$I_{D1} = 8.0A$
$t_{\text{d(off)}}$	Turn-Off Delay Time			72	ns	$R_G = 9.1\Omega$
t <sub>f</sub>	Fall Time			51		V <sub>GS</sub> = 10V
Ls +L <sub>D</sub>	Total Inductance		6.1		nH	Measured from Drain lead (6mm / 0.25 in from package) to Source lead (6mm/ 0.25 in from package)
C <sub>iss</sub>	Input Capacitance		1300			V <sub>GS</sub> = 0V
$C_{oss}$	Output Capacitance		310		pF	V <sub>DS</sub> = 25V
$C_{rss}$	Reverse Transfer Capacitance		120			f = 1.0MHz

## **Source-Drain Diode Ratings and Characteristics**

Symbol	Parameter	Min.	Тур.	Max.	Units	Test Conditions
Is	Continuous Source Current (Body Diode)			8.0	^	
I <sub>SM</sub>	Pulsed Source Current (Body Diode) ①			32	Α	
$V_{SD}$	Diode Forward Voltage			1.5	V	$T_J = 25^{\circ}C, I_S = 8.0A, V_{GS} = 0V$
t <sub>rr</sub>	Reverse Recovery Time			700	ns	$T_J = 25^{\circ}C, I_F = 8.0A, V_{DD} \le 50V$
$Q_{rr}$	Reverse Recovery Charge			8.9	μC	di/dt = 100A/µs ④
t <sub>on</sub>	Forward Turn-On Time	Intrinsic turn-on time is negligible (turn-on is dominated by $L_S + L_D$ )				

## **Thermal Resistance**

Symbol	Parameter	Min.	Тур.	Max.	Units
$R_{\theta JC}$	Junction-to-Case			1.0	°C/W
$R_{\theta JA}$	Junction-to-Ambient (Typical socket mount)			30	C/VV

#### Footnotes:

- ① Repetitive Rating; Pulse width limited by maximum junction temperature.
- $^{\circ}$  V<sub>DD</sub> = 50V, starting T<sub>J</sub> = 25°C, L = 21.88mH, Peak I<sub>L</sub> = 8.0A.
- 3 I<sub>SD</sub>  $\leq$  8.0A, di/dt  $\leq$  100A/ $\mu$ s, V<sub>DD</sub> = 500V, T<sub>J</sub>  $\leq$  150°C.Suggested RG = 9.1 $\Omega$



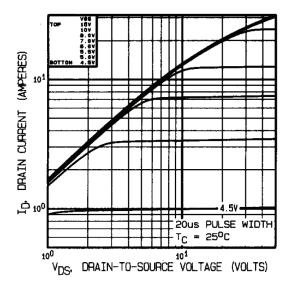


Fig 1. Typical Output Characteristics

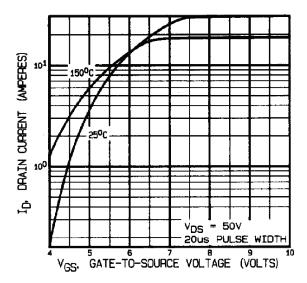


Fig 3. Typical Transfer Characteristics

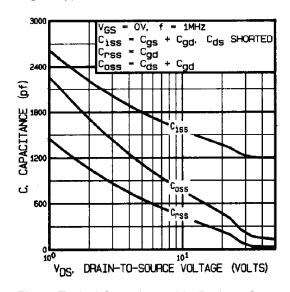


Fig 5. Typical Capacitance Vs. Drain-to-Source Voltage

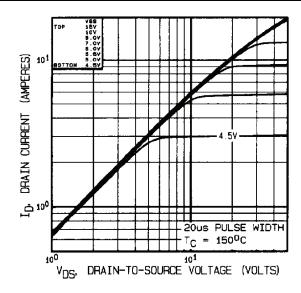


Fig 2. Typical Output Characteristics

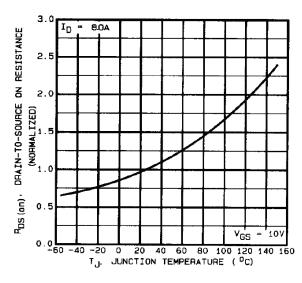


Fig 4. Normalized On-Resistance Vs. Temperature

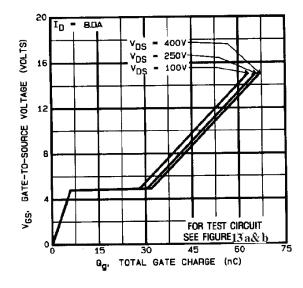


Fig 6. Typical Gate Charge Vs. Gate-to-Source Voltage



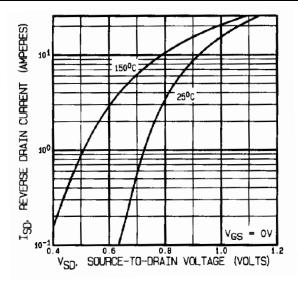


Fig 7. Typical Source-Drain Diode Forward Voltage

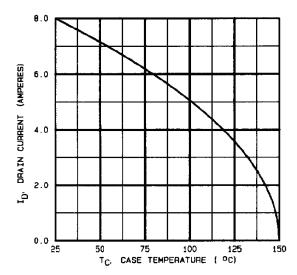


Fig 9. Maximum Drain Current Vs. Case Temperature

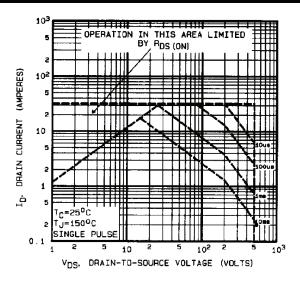
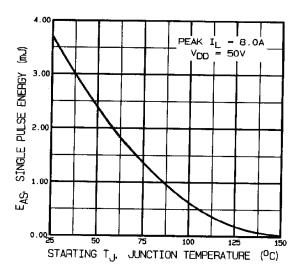


Fig 8. Maximum Safe Operating Area



**Fig 10.** Maximum Avalanche Energy Vs. Drain Current

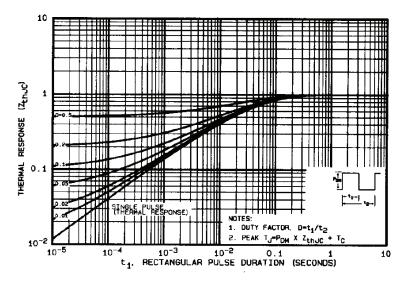


Fig 11. Maximum Effective Transient Thermal Impedance, Junction-to-Case



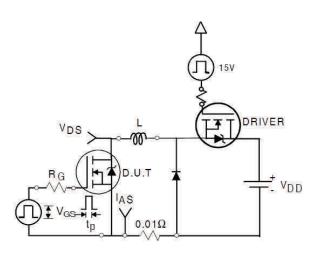


Fig 12a. Unclamped Inductive Test Circuit

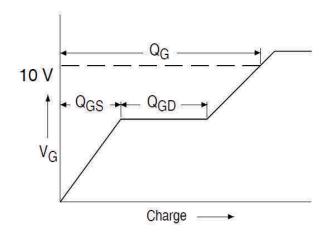


Fig 13a. Gate Charge Waveform

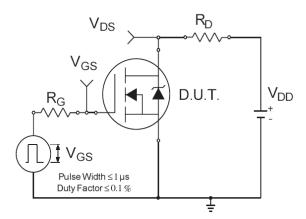


Fig 14a. Switching Time Test Circuit

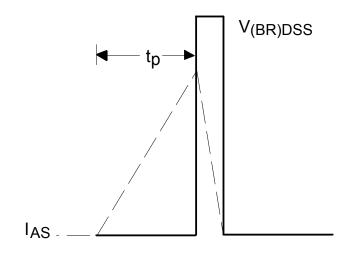


Fig 12b. Unclamped Inductive Waveforms

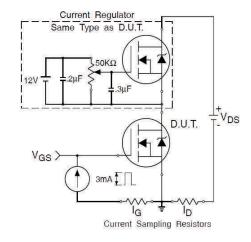


Fig 13b. Gate Charge Test Circuit

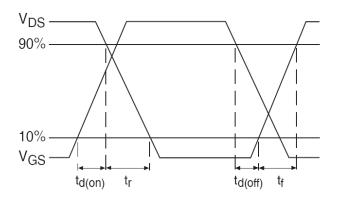
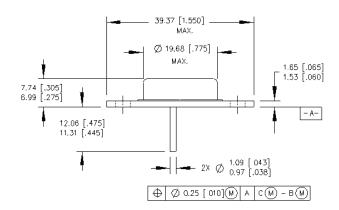
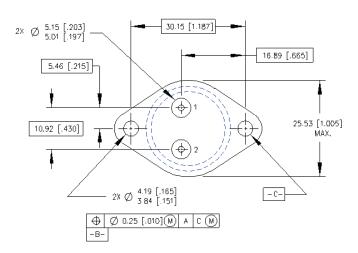


Fig 14b. Switching Time Waveforms



## Case Outline and Dimensions - TO-204AA (Modified TO-3)





#### PIN ASSIGNMENTS

**HEXFET SCHOTTKY** <u>IGBT</u> 1 - SOURCE 1 - ANODE 1 1 - GATE 2 - GATE 3 - DRAIN (CASE) 2 - EMITTER 3 - COLLECTOR (CASE) 2 - ANODE 2 3 - COMMON CATHOD (CASE)

#### NOTES:

- DIMENSIONING & TOLERANCING PER ANSI Y14.5M 1982.
   CONTROLLING DIMENSION : INCH.

- DIMENSIONS ARE SHOWN IN MILIMETERS [ INCHES]
   OUTLINE CONFORMS TO JEDEC OUTLINE TO -204-AA



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